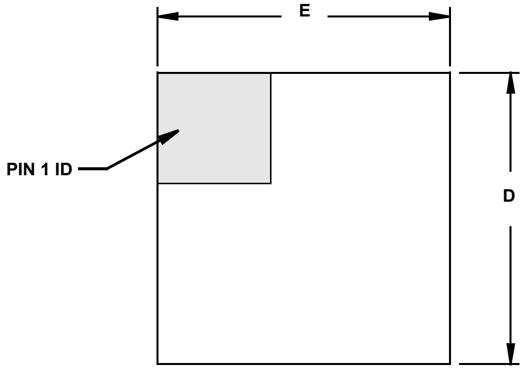
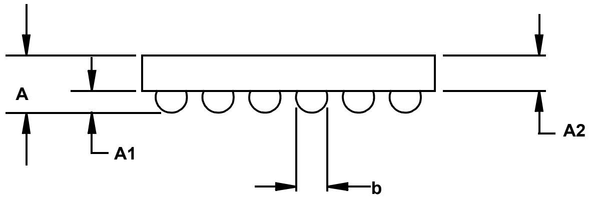
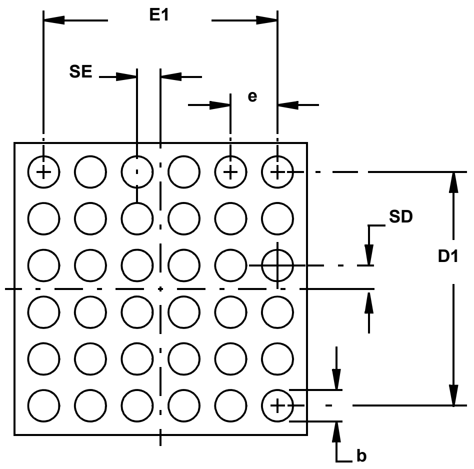
Wafer Level Chip Scale Package (WLCSP)



TOP VIEW



SIDE VIEW



BOTTOM VIEW

W6x6.36

6x6 ARRAY 36 BALL WAFER LEVEL CHIP SCALE PACKAGE

SYMBOL	MILLIMETERS
A	0.44 Min, 0.495 Nom, 0.55 Max
A_1	0.190 ±0.030
A_2	0.305 ±0.025
b	0.270 ±0.030
D	2.530 ±0.020
D_1	2.000 BASIC
E	2.530 ±0.020
E_1	2.000 BASIC
e	0.400 BASIC
SD	0.200 BASIC
SE	0.200 BASIC
Number of Bumps: 36	

Rev. 0 6/08

NOTES:

1. Dimensions are in millimeters.